

RoHS

Specification

规格书

Customer Name : _____

客户名称 :

Customer P/N : _____

客户品号 :

Factory P/N : HL-A-7020D61W-S1-PCT-R

公司品号 :

Sending Date : _____

送样日期 :

Client approval 客户审核			Hongli approval 鸿利光电审核		
Approval 核准	Audit 确认	Confirmation 制作	Approval 核准	Audit 确认	Confirmation 制作
☐ Qualified 接受		☐ Disqualified 不接受	DATE: 日期:		

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注:1. 此规格书以中英文方式书写,若有冲突以中文版本为准文本.

2. 此规格书的最终解释权归广州鸿利光电股份有限公司

3. 此规格书的有效期限为两年,自盖章或签字之日起计算,期满时双方可以续签协议,但应采用书面形式

HL-A-7020D61W-S1-PCT-R

Features(特征)

- Extremely wide viewing angle. (宽的发光角度)
- Suitable for all SMT assembly and solder process. (适用于所有的SMT组装和焊接工艺)
- Available on tape and reel. (适用于载带及卷轴)
- Moisture sensitivity level: Level 4. (防潮等级 Level 4)
- Package:2000pcs/reel..(包装每卷2000PCS)
- RoHS compliant. (RoHS 认证)



Description (描述)

The White LED which was fabricated using a blue chip and the phosphor
白光LED由蓝光芯片与荧光粉激发而成



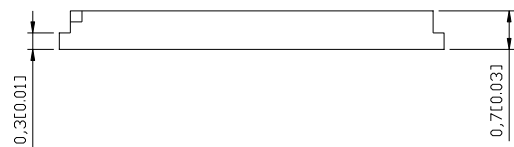
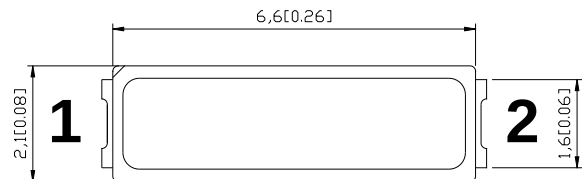
ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

注意：操作时应注意静电敏感
释放设备装置

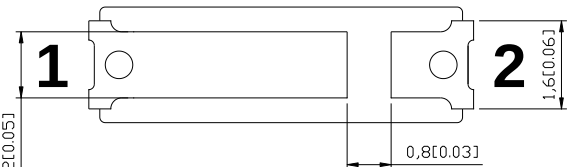
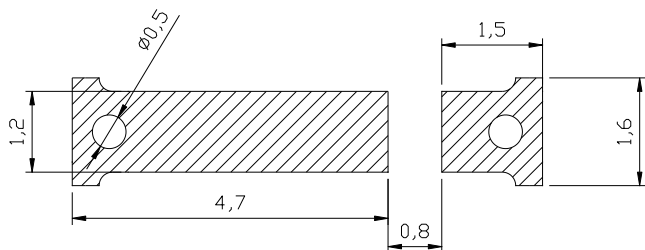
Applications (应用)

- Backlight for LCD, switch and Symbol, display
(LCD背光、转换器, 开关和标志, 显示器等)

Package Dimensions (封装尺寸)



Recommended Soldering Pattern (建议焊盘尺寸图)



Notes: (备注)

1. All dimension units are millimeters. (所有标注尺寸单位为毫米)
2. All dimension tolerance is $\pm 0.15\text{mm}$ unless otherwise noted. (除特别标注外, 所有尺寸允许公差 $\pm 0.15\text{mm}$)

HL-A-7020D61W-S1-PCT-R

Selection Guide (选择指南)

Part No. 型号	Dice	Lens Type
HL-A-7020D61W-S1-PCT-R	White(InGaN)	Yellow Diffused

Mass Production list (批量生产目录)

Part No. 型号	(X,Y) Typ	Φ (lm) Min	Φ (lm) Typ	Test Conditions 测试条件
A-7020D61W-S1-PCT-R	0.265 · 0.235	47	51	I _F =150mA
	0.27 · 0.245	49	53	I _F =150mA

Note:(备注)

- 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
01/2 是半值角, 指光强是光学中心线光强的1/2处到光学中心线的角度
- the above luminous intensity measurement allowance tolerance $\pm 10\%$.
上述发光强度的测试允许公差为 $\pm 10\%$

Electrical / Optical Characteristics at Ta=25°C 电性与光学特性

Parameter (参数)	Symbol (符号)	Min. (最小)	Typ. (平均)	Max. (最大)	Units (单位)	Test Conditions 测试条件
Forward Voltage 正向电压	V _F	2.9	--	3.6	V	I _F =150mA
Reverse Current 反向电流	I _R	--	--	5	μ A	V _R = 5V

Absolute Maximum Ratings at Ta=25°C 绝对最大额定值

Parameter (参数)	Symbol (符号)	Rating (值)	Units (单位)
Power Dissipation (功耗)	P _d	500	mW
Forward Current (正向电流)	I _F	150	mA
Peak Forward Current [1] (峰值正向电流)	I _{FP}	200	mA
Reverse Voltage (反向电压)	V _R	5	V
Electrostatic Discharge (HBM) (静电)	ESD	2000	V
Operating Temperature (操作温度)	T _{opr}	-40 ~ +85	°C
Storage Temperature (保存温度)	T _{stg}	-40 ~ +100	°C
Thermal Resistance (Junction / Soldering point) (结壳热阻)	R _{th J-S}	10	°C/W
Junction Temperature结温	T _j	115	°C

Note: (备注)

- 1/10 Duty cycle, 0.1ms pulse width. (脉宽0.1ms,周期1/10)
- The above forward voltage measurement allowance tolerance is $\pm 0.1V$. (以上所示电压测量误差 $\pm 0.1V$)
- The above color coordinates measurement allowance tolerance is ± 0.003 . (以上所示坐标测量误差 ± 0.003)

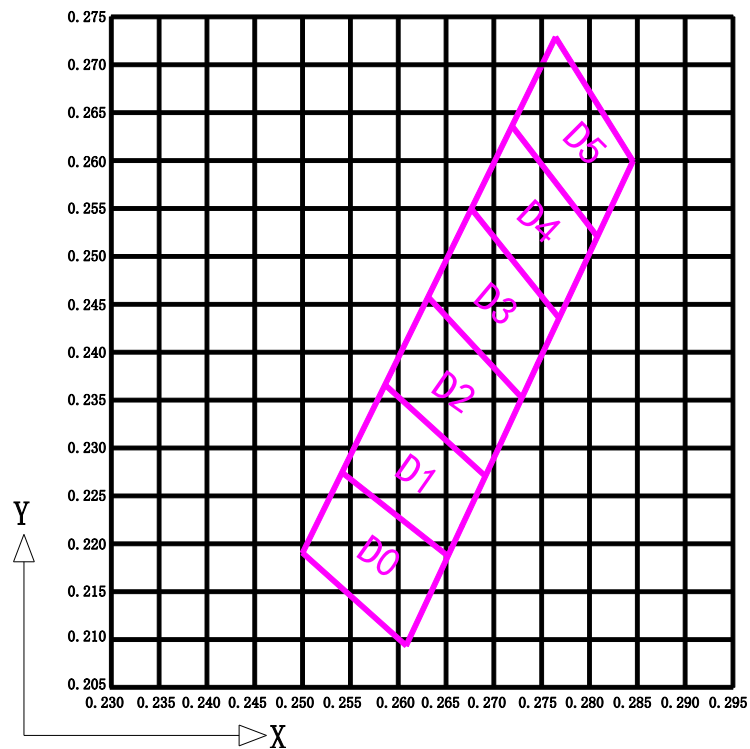
HL-A-7020D61W-S1-PCT-R

BIN	IV (lm)
16a	46-47
16b	47-48
17a	48-49
17b	49-50
18a	50-51
18b	51-52
19a	52-53
19b	53-54
20a	54-55
20b	55-56

BIN	WL
D5	D5
D4	D4
D3	D3
D2	D2
D1	D1

BIN	VF (V)
B	2.8-2.9
C	2.9-3.0
D	3.0-3.1
E	3.1-3.2
F	3.2-3.3
G	3.3-3.4
H	3.4-3.5
I	3.5-3.6

CIE 1931 Chromaticity Diagram :FHDTV



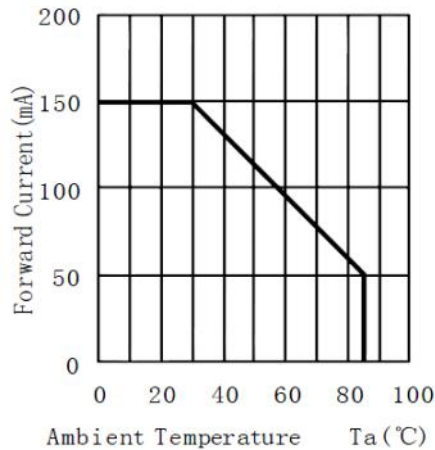
色区 GROUP	Left down		Left up		Right up		Right down	
	X1	Y1	X2	Y2	X3	Y3	X4	Y4
D5	0.2719	0.2636	0.2764	0.2729	0.2845	0.2599	0.2808	0.2521
D4	0.2676	0.2550	0.2719	0.2636	0.2808	0.2521	0.2768	0.2436
D3	0.2631	0.2458	0.2676	0.2550	0.2768	0.2436	0.2729	0.2352
D2	0.2586	0.2366	0.2631	0.2458	0.2729	0.2352	0.2691	0.2271
D1	0.2542	0.2274	0.2586	0.2366	0.2691	0.2271	0.2652	0.2187
D0	0.2500	0.2191	0.2542	0.2274	0.2652	0.2187	0.2608	0.2094

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Typical optical characteristics curves 典型光学特性曲线

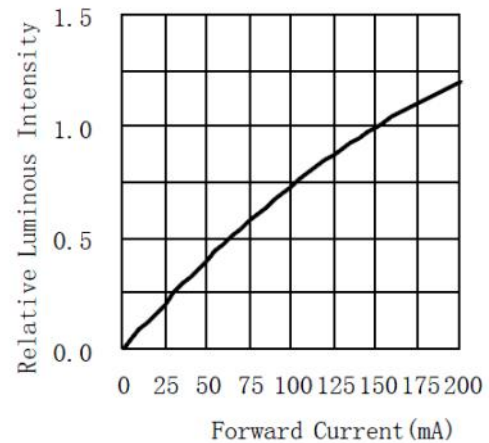
Ambient Temperature vs. Forward Current

环境温度与正向电流特性曲线



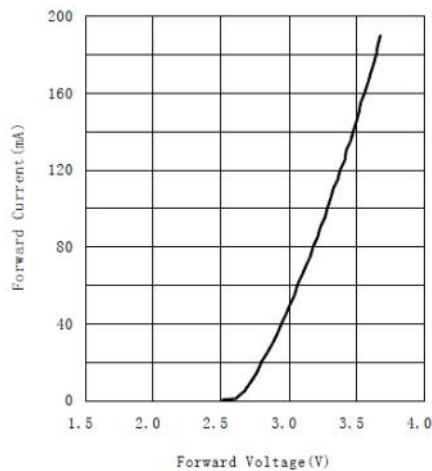
Forward Current VS. Relative Intensity

正向电流与相对光强特性曲线



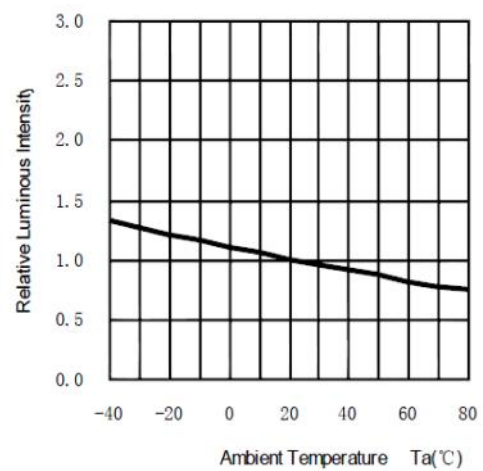
Forward Voltage VS. Forward Current

正向电压与正向电流特性曲线



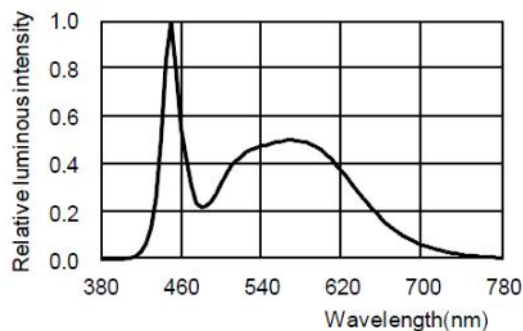
Ambient Temperature VS. Relative Intensity

环境温度与相对光强特性曲线



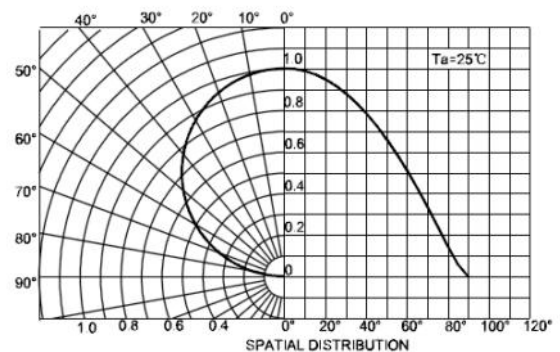
Relative spectral emission

相对光谱分布特性曲线



Radiation diagram

辐射图特性曲线



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Reliability Test Items And Conditions 信赖性测试项目及条件

Test Items 项目	Ref.Standard 参考标准	Test Condition 测试条件	Time 时间	Quantity 数量	Ac/Re 接收/拒收
Reflow 回流焊	JESD22-B106	Temp:260°C max T=10 sec	3 times.	22Pcs.	0/1
Temperature Cycle 温度循环	JESD22-A104	100°C±5°C 30 min. ↑↓5 min -40°C±5°C 30 min.	100 Cycles	22Pcs.	0/1
High Temperature Storage 高温保存	JESD22-A103	Temp:100°C±5°C	1000Hrs.	22Pcs.	0/1
Low Temperature Storage 低温保存	JESD22-A119	Temp:-40°C±5°C	1000Hrs.	22Pcs.	0/1
Life Test 常温通电	JESD22-A108	Ta=25°C±5°C IF=150mA	1000Hrs.	22Pcs.	0/1
High Temperature High Humidity 高温高湿保存	JESD22-A101	85°C±5°C / 85%RH	1000Hrs.	22Pcs.	0/1

Criteria For Judging Damage 失效判定标准

Test Items 项目	Symbol 符号	Test Condition 测试条件	Criteria For Judgement 判定标准	
			Min. 最小	Max. 最大
Forward Voltage 正向电压	VF	IF=150mA	--	U.S.L*)x1.1
Luminous Intensity 光强	mcd	IF=150mA	L.S.L*)x0.7	--

U.S.L: Upper standard level 规格上限

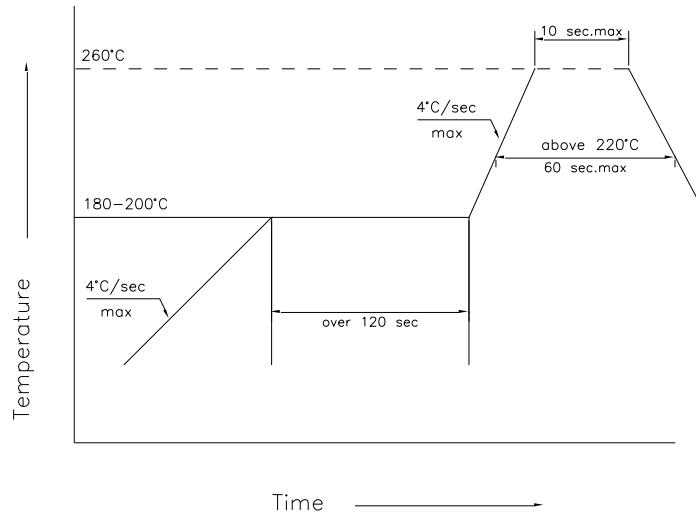
L.S.L: Lower standard level 规格下限

*The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

数据工作表中所示的技术信息仅限于典型特征和电路实例引用的产品。它既不构成工业特性的保证, 也不构成任何许可的授权

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SMT Reflow Soldering Instructions SMT回流焊说明



1. Reflow soldering should not be done more than two times. 回流焊不可以做两次以上
2. When soldering, do not put stress on the LEDs during heating

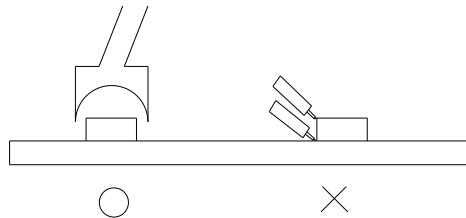
Soldering iron 烙铁焊接

1. When hand soldering, keep the temperature of iron below less 300°C less than 3 seconds

当手工焊接时，烙铁的温度必须小于300°C，时间不可超过3秒

Repairing 修补

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.



Cautions 注意事项

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper.

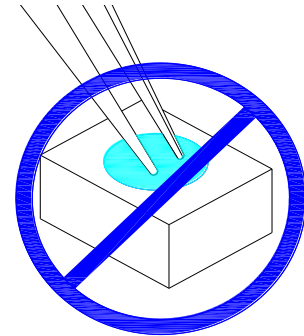
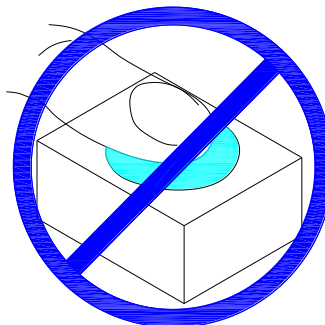
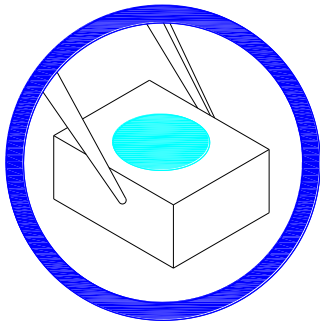
HL-A-7020D61W-S1-PCT-R

Handling Precautions 处理防备措施

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more prone to damage by external mechanical force. As a result, Special handling precautions must be observed during assembling using silicone encapsulated LED products, Failure to comply might leads to damage and premature failure of the LED.

相对环氧树脂较脆较硬而言，硅胶封装较柔软且有弹性，虽然它的特性大大减少了热应力，但易受机械外力损坏，因此

1.Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



2.The outer diameter of the SMD pickup nozzle should not exceed the size

of the LED to prevent air leaks. The inner diameter of the nozzle should be

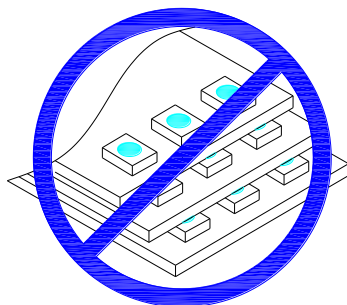
as large as possible. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.

The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid



3.Do not stack together assembled PCBs containing LEDs. Impact may scratch the silicone lens or damage the internal circuitry

不可将模组材料堆积在一起，它可能会损坏内部电路



4.Not suitable to operate in acidic environment, PH<7

不可用在PH<7的酸性场所

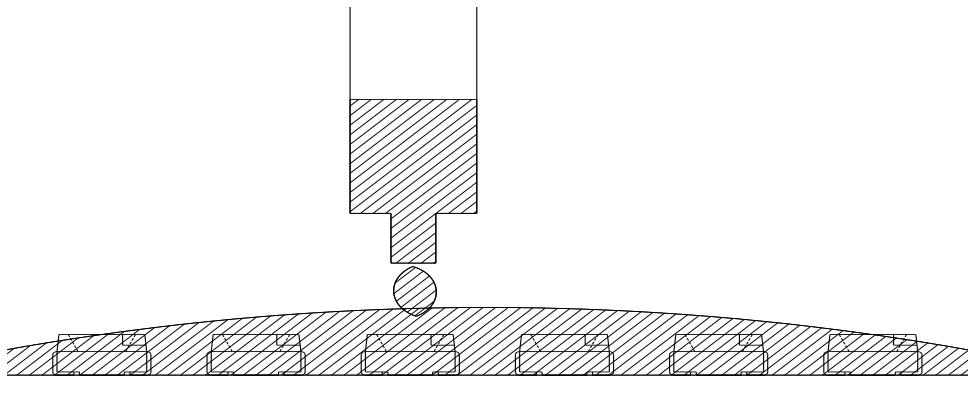


5.LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material.

LED工作环境及与LED适配的材料中硫元素及化合物成份不可超过100PPM

6.When we need to use external glue for LED application products, please make sure that the external glue matches the LED packaging glue. Additionally ,as most of LED packaging glue is silica gel, and it has strong Oxygen permeability as well as strong moisture permeability; in order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine element is required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external glue of the application products is required to be less than 1500PPM

当我们需要使用外封胶涂抹LED产品时，应确保外封胶与LED封装胶水相匹配，因为大多数LED的封装胶水为硅胶，它有较强的氧化性和较强的吸湿性，必须防止外封材质进入LED内部以造成LED的损伤，单一的溴元素含量要求小于900PPM，单一氯元素含量要求小于900PPM，在涂抹LED产品时要求外封胶溴元素与氯元素总含量必须小于1500PPM



7.Other points for attention, please refer to our LED user manual.

其它注意事项请参照我们的LED使用手册

修订次数	修订人	修订内容	修订日期	版次
1	钟嘉威	生成文件	2014-3-10	A/0
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